

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier   |  | User Part Number  |             |           |            |           |  |
|--|--|---|-------------|-----------|------------|-----------|--|
| Nexperia B.V.  Name of Laboratory  Assembly reliability labs  Based on AEC-Q101 Test |  | PDZ22BGW Part Description                                 |             |           |            |           |  |
|  |  |   |             |           |            |           |  |
|  |  | SMD package   |             |           |            |           |  |
|  |  | Test Conditions   | Duration    | # Lots    | # Quantity | # Rejects |  |
|  |  |   | TEST        |           |            |           |  |
|  | Pre- and Post-Stress                           |   |             |           |            |           |  |
| # E1   | Electrical Test                                | Tamb = 25 °C  | N/A         | see below | all parts  | see below |  |
|  |  | JESD22-A113<br>Bake Tamb = 125 °C                         | 24 hours    |           |            |           |  |
|  | PC   | Soak Tamb = 125 °C, RH = 85%                              | 168 hours   |           |            |           |  |
| # A1   | Preconditioning                                | Reflow soldering  | 3 cycles    | 810       | 58300      | 0         |  |
|  |  | MIL-STD-750-1   |             |           |            |           |  |
|  | HTRB   | M1038 Method A  |             |           |            |           |  |
|  |  | Tj = Tjmax, Vr = 100% of max. datasheet                   |             |           |            |           |  |
| # B1   | Bias   | reverse voltage   | 1000 hours  | 138       | 11040      | 0         |  |
|  |  | MIL-STD-750-1   |             |           |            |           |  |
|  | SSOP   | M1038 Method B<br>Tj = Tjmax, Iz = 100% of max. datasheet |             |           |            |           |  |
| # B1b  | Steady State Operational                       | reverse current   | 1000 hours  | 20        | 1600       | 0         |  |
| # 010  | Steady State Specialisms                       | Tovelse darrent   | 1000 110013 | 20        | 1000       | 0         |  |
|  | тс   | JESD22-A104   |             |           |            |           |  |
| # A4   | Temperature Cycling                            | -65 °C to Tjmax, not to exceed 150°C                      | 1000 cycles | 170       | 13600      | 0         |  |
|  |  | JESD22-A102   |             |           |            |           |  |
|  | AC   | Tamb = 121 °C, RH = 100 %                                 |             |           |            |           |  |
| # A3 alt   | Autoclave                                      | Pressure = 205 kPa (29.7 psia)                            | 96 hours    | 170       | 13600      | 0         |  |
| l  |  | 150500 4404   |             |           |            |           |  |
|  | H3TRB  | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of       |             |           |            |           |  |
| # A2 alt   | High Humidity High<br>Temperature Reverse Bias |   | 1000 hours  | 170       | 13600      | 0         |  |
| # AZ dil   | remperature neverse bias                       | MIL-STD-750 Method 1037                                   | 1000 Hours  | 1/0       | 13000      | U         |  |
|  | IOL  | ton = toff, devices powered to insure $\Delta T_i$ =      |             |           |            |           |  |
| # A5   | Intermittent Operating Life                    |   | 1000 hours  | 170       | 13600      | 0         |  |
| -  | · · ·  | ·   |             | -         |            |           |  |
|  | RSH  | JESD22-A111   |             |           |            |           |  |
| # C8   | Resistance to Solder Heat                      | 260 °C ± 5 °C   | 10 s        | 130       | 3900       | 0         |  |
|  | SD   | 1.070.000   |             |           |            |           |  |
| # C10  | Solderability                                  | J-STD-002   |             | 363       | 3630       | 0         |  |

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Zener      | 11040    | 0       | 0.38               | 2.60E+09   |

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